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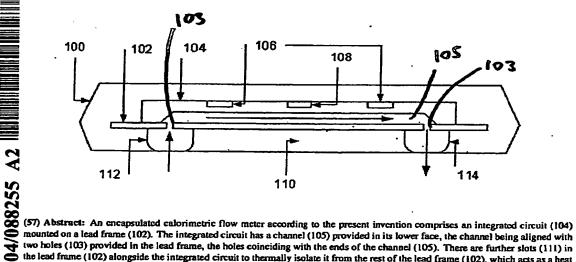
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(54) Title: CALORIMETRIC FLOW METER



the lead frame (102) alongside the integrated circuit to thermally isolate it from the rest of the lead frame (102), which acts as a heat sink to keep the entry and exit fluid at ambient temperature. The flow meter is manufactured by mounting the integrated circuit (104) on to a suitable lead frame (102). The assembly of integrated circuit (104) and lead frame (102) is then inverted and blobs of gel (112, 114) are then deposited onto the lead frame (102) covering the holes (103). The assembly is then inserted into a mould (100) and encapsulated within a suitable mould compound. When the assembly is ejected from the mould cavity the gel can be removed and the holes (103) and the channel (105) exposed to facilitate fluid flow into, out of and along the channel (105).